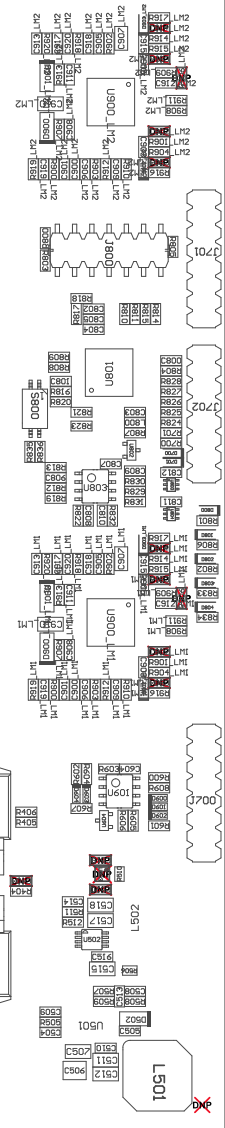
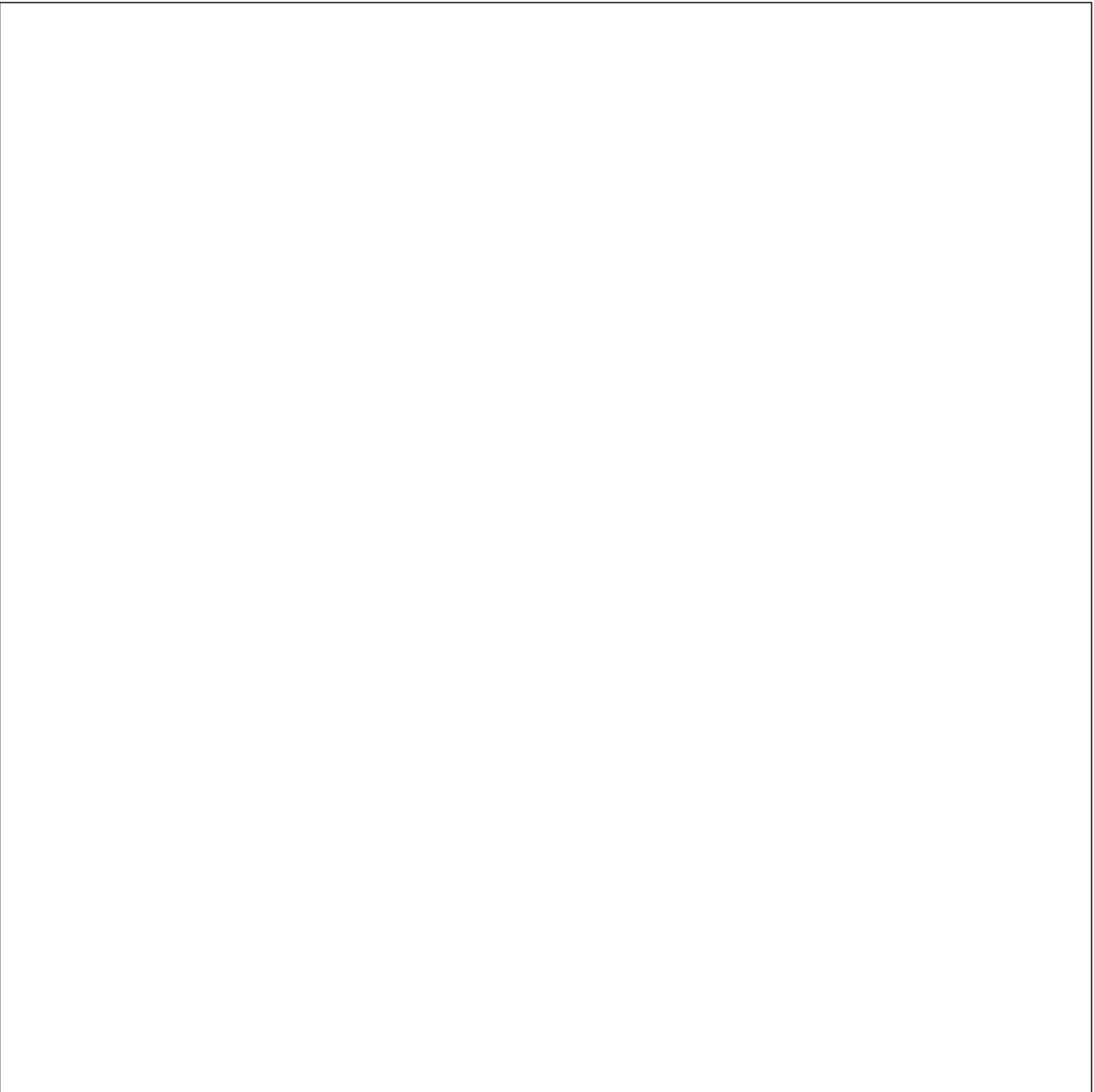


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
Install label in silkscreened box after final wash. Text shall be 8 pt font.
- Z21 ■ Text shall be per the Label Table in the PDF schematic.



PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01168	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDA-01168		
PLOT NAME = Top Assembly Drawing	GENERATED : 17-May-17	2:56:17 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01168	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDA-01168		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 17-May-17	2:56:19 PM	TEXAS INSTRUMENTS

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